



max. operating time < 2secs
 heat sink needed for test purposes only
 For series do not use THT, use SMD:
 ONsemi MBR30HCT-1G

- NOTES:
- 1) R9 for test purposes only
 - 2) dmax 40% @ 6Vin, dmin 5% @ 9.5Vin
 - 3) Inductor: lpk = 19.63A, di = 5.26A @ 6Vin
 - 4) use FET w/ low gate charge, here Si7686DB w/ 17nCtyp, 26nCmax

full load w/ SMD rectifier <20 secs
 half load w/ SMD rectifier <180secs
 full load w/ THT rectifier & heatsink < 180 secs
 half load w/ THT rectifier & heatsink continuous

Texas Instruments

Title TPS40210 9.5V@10Amax Boost		
Size B	Number PMP2661	Rev A
Date 08/01/2008	Drawn by B.Geck	
Filename PMP2661RevA.sch	Sheet 1 of 1	

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